



PATENT APPLICATION

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of

Docket No: Q79041

Youichi KUKIMOTO, et al.

Appln. No.: 10/765,931

Group Art Unit: 2823

Confirmation No.: 1863

Examiner: Khiem D. Nguyen

Filed: January 29, 2004

For: SOLDER DEPOSITION METHOD AND SOLDER BUMP FORMING METHOD

PETITION FOR EXTENSION OF TIME UNDER 37 C.F.R. § 1.136

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

Pursuant to 37 C.F.R. § 1.136, Applicant hereby petitions for an extension of time of one month, extending the time for responding to the Office Action of August 5, 2005, to December 5, 2005.

A check for the statutory fee of \$120.00 is attached. The USPTO is directed and authorized to charge all required fees, except for the Issue Fee and the Publication Fee, to Deposit Account No. 19-4880. Please also credit any overpayments to said Deposit Account. A duplicate copy of this sheet is enclosed.

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CUSTOMER NUMBER

Date: December 2, 2005

Respectfully submitted,

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